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states:(71) Applicant: **MITSUBISHI ELECTRIC CORP**(72) Inventor: **YOSHIDA MIYOSHI  
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**(54) IDENTIFYING METHOD  
FOR SEMICONDUCTOR  
CHIP**

(57) Abstract:

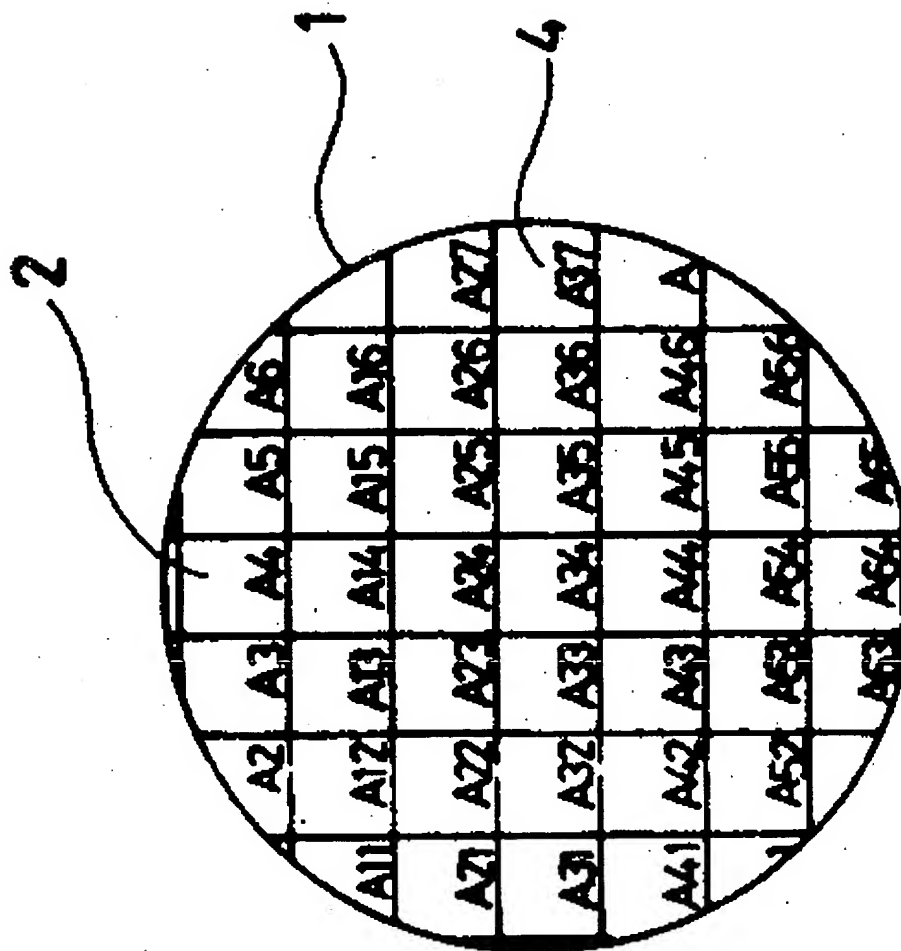
**PURPOSE:** To improve the efficiency percentage of semiconductor chips, by a method wherein each of chips formed in the same wafer in one lot is provided with an individual mark, thereby allowing each chip to be identified.

**CONSTITUTION:** Each of a plurality of chips 2 formed in the same wafer 1 is provided with an individual identification mark 4, e.g., an individual number. After the identification mark 4 is read and stored by means of a TV camera or the like, electrical characteristics of each chip 2 is measured to judge the quality thereof and the rank to which the chip belongs if it is good, and the result is also stored. Upon completion of measurement for all the chips, the wafer 1, together with the mark and judging result of each chip 2, is sent

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to the subsequent assembling step,  
where the chips cut are sorted  
according to their characteristics and  
then assembled.

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